2015 IEEE Symposium on Electromagnetic Compatibility and Signal Integrity

(EMC&SI 2015)

Santa Clara, California, USA
15-21 March 2015

IEEE Catalog Number: CFP1568X-POD
ISBN: 978-1-4799-1994-9

TABLE OF CONTENTS – TECHNICAL PAPERS

TUESDAY TECHNICAL PAPERS

Tuesday, March 17, 2015

TU-AM-1 EMC Management

Chair: Kimball Williams, IEEE Southeastern Michigan Section, Dearborn, MI, USA

10:30 am **China CCC Implementation Rules** 1
Grace Lin *(Intertek, Lake Forest, CA, USA)*

11:00 am **A New Framework for the EU EMC Directive – The European Union New Legislative Framework and New EMC Directive** 7
Mark W. Maynard *(SIEMIC, Inc., Milpitas, CA, USA)*

TU-AM-2 Passive Component Modeling and Measurement I

Chair: Jim Nadolny, Samtec, Inc., New Albany, IN, USA
Co-Chair: Zhichao Zhang, Intel Corp., Chandler, AZ, USA

11:30 am **Suppression of Cavity Resonant Edge Effects and PDN Impedance using Absorbing Material** 12
Shaowu Huang *(Intel Corporation, DuPont, WA, USA);* Gary Charles *(Intel Corporation, DuPont, WA, USA);* Kai Xiao *(Intel Corporation, Dupont, WA, USA);* Beomtaek Lee *(Intel Corporation, Santa Clara, CA, USA);* Gong Ouyang *(Intel Corporation, Dupont, WA, USA);* Hanqiao Zhang *(Intel Corporation, DuPont, WA, USA)*

TU-AM-3 Jitter/Noise Modeling and Analysis I

Chair: Brice Achkir, Cisco Systems, Inc., San Jose, CA, USA
Co-Chair: Fangyi Rao, Agilent Technologies, Santa Clara, CA, USA

10:30 am **Reducing Power-Supply and Ground Noise Induced Timing Jitter in Short Pulse Generation Circuits** 17
Jiwei Sun *(Clemson University, Clemson, SC, USA);* Pingshan Wang *(Clemson University, Clemson, SC, USA);* Hanqiao Zhang *(Intel Corporation, DuPont, WA, USA)*

11:00 am **On-Chip Linear Voltage Regulator Module (VRM) Effect on Power Distribution Network (PDN) Noise and Jitter at High-Speed Output Buffer** 22
Heegon Kim *(KAIST, Daejeon, South Korea);* Sukjin Kim *(KAIST, Daejeon, South Korea);* Joungho Kim *(KAIST, Daejeon, South Korea);* Jingook Kim *(Ulsan National Institute of Science and Technology, Ulsan, South Korea);* Changwook Yoon *(Altera Corporation, San Jose, CA, USA);* Brice Achkir *(Cisco Systems, Inc., San Jose, CA, USA);* Jun Fan *(Missouri University of Science and Technology, Rolla, MO, USA)*
Best SIPI Paper Award Finalist

TU-AM-4 Numerical Modeling and Simulation Techniques I

Chair: Dan Jiao, Purdue University, West Lafayette, IN, USA
Co-Chair: Qinghua Bill Chen, Yangtze Delta Region Institute of Tsinghua University, Jiaxing, Zhejiang, China

10:30 am **Physical Interpretation of Radiation and Transfer Characterization based on the PEEC Method** 28
Ying S. Cao *(The Univeristy of Hong Kong, Hong Kong, Hong Kong);* Li Jun Jiang *(The Univeristy of Hong Kong, Hong Kong, Hong Kong);* Albert E. Ruehli *(Missouri University of Science and Technology, Rolla, MO, USA)*

11:00 am **Full-Wave Simulation of an Imbalanced Differential Mircostrip Line with Conductor Surface Roughness** 34
Marina Koledintseva *(Oracle, Menlo Park, CA, USA);* Tracey Vincent *(CST of America, Framingham, MA, USA);* Sergiu Radu *(Oracle, Menlo Park, CA, USA)*

11:30 am **Quality Assurance of S-Parameters and Rational Function Models for Transient Simulations** 40
Sanghoek Kim *(Qualcomm Inc., San Diego, CA, USA);* Gerardo Romo Luevano *(Qualcomm Inc., San Diego, CA, USA);* Kevin Roselle *(Qualcomm Inc., San Diego, CA, USA);*
Tim Michalka *(Qualcomm Inc., San Diego, CA, USA)*
Best SIPI Paper Award Finalist

TU-AM-5 Electromagnetic Environment and ESD

Chair: William Radasky, Metatech Corporation, Goleta, CA, USA

10:30 am **Modal Expansion Basis for Statistical Estimation of Maximum Expected Field Strength in Enclosures** 46
Paul G. Bremner *(Robust Physics, Del Mar, CA, USA)*
Best EMC Paper Award Finalist

11:00 am **Modeling Atmospheric Turbulence and Noise as Electromagnetic Interference** 52
Robert McMillan *(Consultant, St George Island, FL, USA);* Ira Kohlberg *(Kohlberg Associates, Reston, VA, USA)*

11:30 am **Electrostatic Charging caused by Standing up from a Chair and by Garment Removal** 57
Atieh Talebzadeh *(Missouri University of Science and Technology, Rolla, MO, USA);*
Mahdi Moradian *(Missouri University of Science and Technology, Rolla, MO, USA);*
Yunan Han *(Missouri University of Science and Technology, Rolla, MO, USA);*
David E. Swenson *(Affinity Static Control Consulting, L.L.C, Round Rock, TX, USA);*
David Pommerenke *(Missouri University of Science and Technology, Rolla, MO, USA)*
Best Student Paper Award Finalist

TU-PM-1 Special Session: Radio-Frequency Interference and Wireless EMC

Chair: Harry Skinner, Intel Corporation, Hillsboro, OR, USA
Co-Chair: David Pommerenke, Missouri University of Science and Technology, Rolla, MO, USA
Co-Chair: Perry Wilson, National Inst. of Standards and Technology (NIST), Boulder, CO, USA

1:30 pm **Measuring a Device's Susceptibility to LTE: Preliminary Approaches** 63
Jason B. Coder *(National Institute of Standards and Technology, Boulder, CO, USA);*
John M. Ladbury *(National Institute of Standards and Technology, Boulder, CO, USA);*
William F. Young *(National Institute of Standards and Technology, Boulder, CO, USA)*

2:00 pm **A Review of Wireless Coexistence Test Methodologies** 69
William F. Young *(National Institute of Standards and Technology, Boulder, CO, USA);*
Jason B. Coder *(National Institute of Standards and Technology, Boulder, CO, USA);*
Luis A. Gonzalez *(University of Colorado, Boulder, CO, USA)*

2:30 pm **Wearables/IOT Devices: Challenges and Solutions to Integration of Miniature Antennas in Close Proximity to the Human Body** 75
Soji Sojuyigbe *(Intel Corporation, Santa Clara, CA, USA);* Kevin Daniel *(Intel Corporation, Hillsboro, OR, USA)*

3:30 pm **Gb/s USB: RFI Risk Analysis and Test Methodologies** 79
Pujitha Davuluri *(Intel Corporation, Hillsboro, OR, USA);* Chung-Hao (Joseph) Chen *(Intel Corporation, Hillsboro, OR, USA);* Kuan-Yu Chen *(Intel Corporation, Hillsboro, OR, USA);* Eric Gantner *(Intel Corporation, Hillsboro, OR, USA)*

4:00 pm **PC Client Platform RFI Risks and Mitigation Methodologies** 85
Dong-Ho Han *(Intel Corporation, Hillsboro, OR, USA);* Hao-Han Hsu *(Intel Corporation, Hillsboro, OR, USA);* Joseph Chen *(Intel Corporation, Hillsboro, OR, USA);* Mike Schaffer *(Intel Corporation, Hillsboro, OR, USA);* Chi M. Cheung *(Intel Corporation, Hillsboro, OR, USA);* Pujitha Davuluri *(Intel Corporation, Hillsboro, OR, USA)*

TU-PM-2 Electromagnetic Interference Control

Chair: John Kraemar, Rockwell Collins, Inc., Cedar Rapids, IA, USA
Co-Chair: Ross Carlton, National Instruments, Austin, TX, USA

1:30 pm **Miniaturization Approach for EBG-Based Common Mode Filter and Interference Analysis** 91
C. Olivieri *(University of L'Aquila, L'Aquila, Italy);* F. de Paulis *(University of L'Aquila, L'Aquila, Italy);* A. Orlandi *(University of L'Aquila, L'Aquila, Italy);* S. Connor *(IBM Corporation, Research Triangle Park, Durham, NC, USA);* B. Archambeault *(IBM Corporation, Research Triangle Park, Durham, NC, USA)*

2:00 pm **A Study of EMI from Patterned Ground Structures** 97
Albert Wallash *(HGST, a Western Digital Company, San Jose, CA, USA);* Jack Nguyen *(HGST, a Western Digital Company, San Jose, CA, USA)*

2:30 pm **A Comparison of Relative Shielding Provided by Stitching vias and Edge Plating** 101
Jim Chiappe *(Juniper Networks, Sunnyvale, CA, USA)*

3:30 pm **2D Imaging System with Optical Tracking for EMI Source Localization** 107
Hui He *(Missouri University of Science and Technology, Rolla, MO, USA);*
Victor Khilkevich *(Missouri University of Science and Technology, Rolla, MO, USA);*
David Pommerenke *(Missouri University of Science and Technology, Rolla, MO, USA)*
Best EMC Paper Award Finalist and Best Student Paper Award Finalist

TU-PM-3 High Speed Link Design I

Chair: Joy Li, Cadence Design Systems, San Jose, CA, USA
Co-Chair: Chunfei Ye, Intel Corporation, DuPont, WA, USA

1:30 pm **Design of Package BGA Pin-Out for >25Gb/s High Speed SerDes Considering PCB via Crosstalk** 111
Wei Yao *(Cisco Systems, Inc., San Jose, CA, USA);* Jane Lim *(Cisco Systems, Inc., San Jose, CA, USA);* Ji Zhang *(Cisco Systems, Inc., San Jose, CA, USA);* Kenneth Tseng *(Cisco Systems, Inc., San Jose, CA, USA);* Kelvin Qiu *(Cisco Systems, Inc., San Jose, CA, USA);* Rick Brooks *(Cisco Systems, Inc., San Jose, CA, USA)*

2:00 pm **Effective Equalization of a High Speed Differential Channel with Re-Driver – Screening and RSM DOE Method Applied to a Real System** 117
Maria J. Garcia *(CINVESTAV Guadalajara, Zapopan, Mexico);* Raul Enriquez *(Intel Tecnologia de Mexico SA de CV, Zapopan, Mexico);* Jose A. Ramos *(Intel Tecnologia de Mexico SA de CV, Zapopan, Mexico)*
Best SIPI Paper Award Finalist

2:30 pm **Method for Accurate and Efficient Signaling Analysis of Nonlinear Circuits** 123
Dan Jiao *(Purdue University, West Lafayette, IN, USA);* Olena (Jianfang) Zhu *(Intel Corporation, Hillsboro, OR, USA)*
Best SIPI Paper Award Finalist

TU-PM-4 SI/PI/EMC Co-Simulation and Co-Design

Chair: Olena Zhu, Intel Corporation, Santa Clara, CA, USA
Co-Chair: Duo Chen, Intel Corporation, Santa Clara, CA, USA

1:30 pm **Signal Integrity and EMI Evaluations of an RFID-Sensor Tag for Internet-of-Things Applications** 128
Abdulhadi E. Abdulhadi *(McGill University, Montreal, QC, Canada);*
Svetoslav Mandev *(Santa Clara University, Santa Clara, CA, USA);*
Ramesh Abhari *(Santa Clara University, Santa Clara, CA, USA)*

2:00 pm **Analytical PDN Voltage Ripple Calculation using Simplified Equivalent Circuit Model of PCB PDN** 133
Biyao Zhao *(Missouri University of Science and Technology, Rolla, MO, USA);* Chenxi Huang *(Missouri University of Science and Technology, Rolla, MO, USA);* Ketan Shringarpure *(Missouri University of Science and Technology, Rolla, MO, USA);* Jun Fan *(Missouri University of Science and Technology, Rolla, MO, USA);* Bruce Archambeault *(Missouri University of Science and Technology, Rolla, MO, USA);* Brice Achkir *(Cisco Systems, Inc., San Jose, CA, USA);* Samuel Connor *(IBM Corporation, Research Triangle Park, Durham, NC, USA);* Michael Cracraft *(IBM Corporation, Poughkeepsie, NY, USA);* Matteo Cocchini *(IBM Corporation, Poughkeepsie, NY, USA);* Albert Ruehli *(Missouri University of Science and Technology, Rolla, MO, USA);* James Drewniak *(Missouri University of Science and Technology, Rolla, MO, USA)*

WEDNESDAY POSTER PAPERS

Wednesday, March 18, 2015

Poster Session

Chair: Jingook Kim, Ulsan National Institute of Science and Technology, Ulsan, South Korea
Co-Chair: Alpesh Bhobe, Cisco Systems, Inc., San Jose, CA, USA
Meet and Greet Authors 1:00 am to 2:30 pm Wednesday.

An Improved Multiple Edge Responses Method for Memory Simulation Considering Worst Case and Nonlinear Crosstalk 139
Shiji Pan *(Inphi Corporation, Santa Clara, CA, USA);* Jiangyuan Qian *(Qualcomm Technologies, Inc., San Diego, CA, USA)*

Common-Mode Noise Reduction on Broadside-Coupled Delay Line 144
Ding-Bing Lin *(National Taipei University of Technology, Taipei City, Taiwan);* Chung-Pin Huang *(National Taipei University of Technology, Taipei City, Taiwan);* Hsin-Nan Ke *(PEGATRON Corporation, Taipei City, Taiwan);* Wen-Sheng Liu *(WIESON Technologies Co., Ltd., New Taipei City, Taiwan)*

Design of a 20 GHz Bandwidth Dual-Stage Dual-FIR Channel Emulator 148
W. Qian *(Missouri University of Science and Technology, Rolla, MO, USA);* A. Talebzadeh *(Missouri University of Science and Technology, Rolla, MO, USA);* G. Li *(Missouri University of Science and Technology, Rolla, MO, USA);* J. Zhou *(Huazhong University of Science & Technology, Wuhan, China);* D. Pommerenke *(Missouri University of Science and Technology, Rolla, MO, USA);* C. Ding *(Cisco Systems, Inc., San Jose, CA, USA);* D. White *(Cisco Systems, Inc., San Jose, CA, USA);* S. Scearce *(Cisco Systems, Inc., San Jose, CA, USA);* Y. Yang *(Cisco Systems, Inc., Research Triangle Park, Durham, NC, USA)*

Reconstruction of Currents from EMC Near-Field Measurements by Means of Continuity Equation Constraints 154
Martin Schmidt *(Friedrich-Alexander-University Erlangen-Nuremberg, Erlangen, Germany);* Manfred Albach *(Friedrich-Alexander-University Erlangen-Nuremberg, Erlangen, Germany)*

Radiation Physics from Two-Wire Transmission Lines 160
Jing Li *(Missouri University of Science and Technology, Rolla, MO, USA);* Yaojiang Zhang *(Missouri University of Science and Technology, Rolla, MO, USA);* Dazhao Liu *(Missouri University of Science and Technology, Rolla, MO, USA);* Alpesh Bhobe *(Cisco Systems, Inc., San Jose, CA, USA);* James L. Drewniak *(Missouri University of Science and Technology, Rolla, MO, USA);* Jun Fan *(Missouri University of Science and Technology, Rolla, MO, USA)*
Best Student Paper Award Finalist

WEDNESDAY TECHNICAL PAPERS

WED-AM-1 Automotive EMC Measurements

Chair: Craig Fanning, Elite Electronic Engineering Inc., Downers Grove, IL, USA

8:30 am **On the Interplay between the Engine Cooling Fan and Heat Exchanger for Automotive AM Band Radiated Emission Measurement** 165
Cyrous Rostamzadeh *(Robert Bosch LLC, Plymouth, MI, USA);* Dennis Schwaiger *(Robert Bosch LLC, Plymouth, MI, USA);* David Maciejewski *(Robert Bosch LLC, Plymouth, MI, USA);* Kimball Williams *(IEEE EMC Past President, Dearborn, MI, USA);* Mark Steffka *(General Motors, Milford, MI, USA)*

9:30 am **Impact of Mismatch Loss on Mobile Phone Simulation for Automotive Testing** 170
R. Keith Frazier *(Ford Motor Company, Dearborn, MI, USA);* Peng Peng *(Ford Motor Company, Nanjing, China)*

WED-AM-2 Passive Component Modeling and Measurement II

Chair: Antonio Ciccomancini, Apple Inc., Cupertino, CA, USA
Co-Chair: Shaowei Deng, F5 Networks, San Jose, CA, USA

8:30 am **Comparison of TRL Calibration vs. 2x thru De-Embedding Methods** 176
Se-Jung Moon *(Intel Corporation, Hillsboro, OR, USA);* Xiaoning Ye *(Intel Corporation, Hillsboro, OR, USA);* Rex Smith *(Intel Corporation, Dupont, WA, USA)*

9:00 am **Investigation of S21 Magnitude Extraction Methodologies by using a Pattern Generator and Sampling Oscilloscope** 181
Xinyun Guo *(Missouri University of Science and Technology, Rolla, MO, USA);* Ketan Shringarpure *(Missouri University of Science and Technology, Rolla, MO, USA);* Fadi Daou *(MultiLane SAL, Santa Clara, CA, USA);* Jun Fan *(Missouri University of Science and Technology, Rolla, MO, USA)*

9:30 am **Investigation of Signal Integrity Issues in Multi-Path Electrostatic Discharge Protection Device** 187
Yang-Chih Huang *(National Taiwan University, Taipei, Taiwan);* Tzong-Lin Wu *(National Taiwan University, Taipei, Taiwan);* Chung-Hao Chen *(Intel Corporation, Portland, OR, USA)*

WED-AM-4 Power Integrity and Power Delivery Network I

Chair: Dale Becker, IBM, Poughkeepsie, NY, USA
Co-Chair: Guang Chen, Altera Corporation, San Jose, CA, USA

9:00 am **Power Archipelago for GHz Power Filtering on Printed Circuit Boards** 193
Chris Ferguson *(San Diego State University, San Diego, CA, USA);* A. Ege Engin *(San Diego State University, San Diego, CA, USA)*

WED-AM-5 Applications of Numerical Modeling

Chair: Vignesh Rajamani, Oklahoma State University, Stillwater, OK, USA
Co-Chair: James West, Oklahoma State University, Stillwater, OK, USA

8:30 am **Analysis of Field Probe Perturbation in a Mode Stirred Reverberation Chamber** 197
Luca Bastianelli *(Università Politecnica delle Marche, Ancona, Italy);* Valter Mariani Primiani *(Università Politecnica delle Marche, Ancona, Italy);* Franco Moglie *(Università Politecnica delle Marche, Ancona, Italy)*

9:00 am **Robust and Efficient RLGC Extraction for Transmission Line Structures with Periodic Three-Dimensional Geometries** 203
Yunhui Chu *(Intel Corporation, Hillsboro, OR, USA);* Jason Zhenwei Yu *(Intel Corporation, Seattle, WA, USA);* Zhiguo Qian *(Intel Corporation, Chandler, AZ, USA)*
Best EMC Paper Award Finalist

9:30 am **An Augmented Electric Field Integral Equation Formulation for Dielectrics and Conductors at Low Frequencies** 209
Tian Xia *(University of Illinois, Urbana-Champaign, Urbana, IL, USA);* Hui Gan *(University of Illinois, Urbana-Champaign, Urbana, IL, USA);* Michael Wei *(University of Illinois, Urbana-Champaign, Urbana, IL, USA);* Weng Cho Chew *(University of Illinois, Urbana-Champaign, Urbana, IL, USA);* Henning Braunisch *(Intel Corporation, Chandler, AZ, USA);* Zhiguo Qian *(Intel Corporation, Chandler, AZ, USA);* Kemal Aygun *(Intel Corporation, Chandler, AZ, USA);* Alaeddin Aydiner *(Intel Corporation, Hillsboro, OR, USA)*
Best EMC Paper Award Finalist and Best Student Paper Award Finalist

THURSDAY TECHNICAL PAPERS

Thursday, March 19, 2015

TH-AM-1 EMC Measurements and Calibration

Chair: Dave Arnett, Hewlett Packard, Vancouver, WA, USA

8:30 am **Characterization and Correction of Calibration Jigs for LISN Impedance Measurements** 215
Alexander Kriz *(Seibersdorf Laboratories, Seibersdorf, Austria)*

9:00 am **A Proposal of Substitution Method for Antenna Calibrations by the use of Absorbers on the Ground Plane at Frequencies from 1 GHz to 18 GHz** 220
Mitsunobu Samoto *(Liberty Labs Asia, Inc., Yokohama, Japan);* Nobuhito Samoto *(Liberty Labs Asia, Inc., Yokohama, Japan);* Ikuo Makino *(Liberty Labs Asia, Inc., Yokohama, Japan)*

10:30 am **Extension and Verification of Absorbing Material Effectiveness on Reducing Electromagnetic Emissions** 226
Eric A. Drake *(Oklahoma State University, Stillwater, OK, USA);* Vignesh Rajamani *(Oklahoma State University, Stillwater, OK, USA);* Charles F. Bunting *(Oklahoma State University, Stillwater, OK, USA);* James C. West *(Oklahoma State University, Stillwater, OK, USA);* Bruce Archambeault *(IBM Corporation, Research Triangle Park, Durham, NC, USA);* Samuel Connor *(IBM Corporation, Research Triangle Park, Durham, NC, USA)*

11:00 am **Received Power and Ambient Electric Field from Broadband Emissions in Reverberant Spaces** 231
Gregory Tait *(Naval Surface Warfare Center - Dahlgren, Dahlgren, VA, USA);* Carl Hager *(Naval Surface Warfare Center - Dahlgren, Dahlgren, VA, USA);* Timothy Baseler *(Naval Surface Warfare Center - Dahlgren, Dahlgren, VA, USA);* Michael Slocum *(Naval Surface Warfare Center - Dahlgren, Dahlgren, VA, USA)*

11:30 am **Maximum Received Power Statistics within RF Reflective Enclosures for HERO/EMV Testing** 237
Carl E. Hager *(Naval Surface Warfare Center - Dahlgren, Dahlgren, VA, USA);*
Gregory B. Tait *(Naval Surface Warfare Center - Dahlgren, Dahlgren, VA, USA)*
Best EMC Paper Award Finalist

TH-AM-2 High Speed Link Design II

Chair: Dan Oh, Altera Corporation, San Jose, CA, USA
Co-Chair: Shaowu Huang, Intel Corporation, DuPont, WA, USA

11:30 am **QSFP28 Connector Footprint Optimization of Crosstalk and ILD_rms_dB for 25+ Gbps Signaling** 242
IL-Young Park *(Cisco Systems, Inc., San Jose, CA, USA);* Minh Quach *(Avago Technologies, San Jose, CA, USA);* Michael Rowlands *(Molex, Inc., Lisle, IL, USA)*

TH-AM-3 Modeling and Simulation for Large-Scale and Multi-Scale Power Delivery Network

Chair: Qing He, Oracle Corporation USA, Santa Clara, CA, USA
Co-Chair: Xiaoning Ye, Intel Corporation, Hillsboro, OR, USA

8:30 am **Dynamic Analysis of Power Delivery Network with Nonlinear Components using Matrix Exponential Method** 248
Hao Zhuang *(University of California, San Diego, La Jolla, CA, USA);* Ilgweon Kang *(University of California, San Diego, La Jolla, CA, USA);* Xinan Wang *(University of California, San Diego, La Jolla, CA, USA);* Jeng-Hau Lin *(University of California, San Diego, La Jolla, CA, USA);* Chung-Kuan Cheng *(University of California, San Diego, La Jolla, CA, USA)*

9:00 am **Fast Transient Simulation of Multilayered Power Delivery Network by using the Stabilized Explicit Method** 253
Tadatoshi Sekine *(Shizuoka University, Hamamatsu-shi, Japan);* Hideki Asai *(Shizuoka University, Hamamatsu-shi, Japan)*

9:30 am **Fast Structure-Aware Direct Time-Domain Finite Element Solver for Large-Scale On-Die Power Grid Simulation** 259
Woochan Lee *(Purdue University, West Lafayette, IN, USA);* Dan Jiao *(Purdue University, West Lafayette, IN, USA)*
Best SIPI Paper Award Finalist

10:30 am **System Power Noise Analysis using Modulated CPM** 265
Di Hu *(Cisco Systems, Inc., San Jose, CA, USA);* Yongxue Yu *(Cisco Systems, Inc., San Jose, CA, USA);* Antonio Ferrario *(STMicroelectronics, Cornaredo, MI, Italy);* Olivier Bayet *(STMicroelectronics, Grenoble, France);* Lin Shen *(Cisco Systems, Inc., San Jose, CA, USA);* Ravi Nimmagadda *(Cisco Systems, Inc., San Jose, CA, USA);* Felice Bonardi *(Cisco Systems, Inc., San Jose, CA, USA);* Francis Matus *(Cisco Systems, Inc., San Jose, CA, USA)*

11:00 am **Vectorless Transient Power Grid Verification: A Case Study with IBM Benchmarks** 271
Xuanxing Xiong *(Synopsys, Inc., Mountain View, CA, USA);* Jia Wang *(Illinois Institute of Technology, Chicago, IL, USA)*
Best SIPI Paper Award Finalist

11:30 am **Impulse Response Generation from S-Parameters for Power Delivery Network Simulation** 277
Ilgweon Kang *(University of California, San Diego, La Jolla, CA, USA);* Xinan Wang *(University of California, San Diego, La Jolla, CA, USA);* Jeng-Hau Lin *(University of California, San Diego, La Jolla, CA, USA);* Ryan Coutts *(University of California, San Diego, La Jolla, CA, USA);* Chung-Kuan Cheng *(University of California, San Diego, La Jolla, CA, USA)*

TH-AM-4 Numerical Modeling Approaches

Chair: Jianmin Zhang, Apple Inc., Cupertino, CA, USA
Co-Chair: Kai Xiao, Intel Corporation, Dupont, WA, USA

8:30 am **Technique to Improve the Accuracy of Mixed-Mode S-Parameters Derived from Single-Ended Results and Application to Shorter Test Coupon Design** 283
Shaowu Huang *(Intel Corporation, DuPont, WA, USA)*

9:00 am **USB3.1 Silicon and Channel Design Optimization using Artificial Neural Network Modeling** 289
Mo Liu *(Intel Corporation, Santa Clara, CA, USA);* Jennifer Hsiao-Ping Tsai *(Intel Corporation, Santa Clara, CA, USA)*

9:30 am **Modeling of Mutual Coupling between Inductors** 294
G. Asmanis *(Riga Technical University, Riga, Latvia);* L. Ribickis *(Riga Technical University, Riga, Latvia);* A. Asmanis *(Riga Technical University, Riga, Latvia);* D. Stepins *(Riga Technical University, Riga, Latvia)*

10:30 am **Rigorous One-Port Measurement Method for the Characterization of On-Chip Pad Response** 300
Shaowu Huang *(Intel Corporation, DuPont, WA, USA);* Beomtaek Lee *(Intel Corporation, Santa Clara, CA, USA);* Xiaoning Ye *(Intel Corporation, Hillsboro, OR, USA);* Kai Xiao *(Intel Corporation, Dupont, WA, USA)*

11:00 am **Software-Related EMI Test Pattern Auto-Generation for 2-Stage Pipeline Microcontroller** 306
Shih-Yi Yuan *(Feng Chia University, Taichung, Taiwan);* Yung-Chi Tang *(Bureau of Standards, Metrology and Inspection, Taipei, Taiwan);* Cheng-Chang Chen *(Bureau of Standards, Metrology and Inspection, Taipei, Taiwan)*

TH-PM-1 Wireless Testing and RF Interference

Chair: Yihong Qi, DBJ Technologies, Zhuhai, China
Co-Chair: William Young, National Institute of Standards and Technology, Boulder, CO, USA

1:30 pm **An Effective Receiver Sensitivity Measurement** 310
Zixin Liu *(Hunan University, Changsha, China);* Fuhai Li *(Hunan University, Changsha, China);* Yihong Qi *(DBJ Technologies, Zhuhai, China);* Ji Chen *(University of Houston, Houston, TX, USA)*

2:00 pm **Conducted-Emission Modeling for a Switched-Mode Power Supply (SMPS)** 314
Yansheng Wang *(Missouri University of Science and Technology, Rolla, MO, USA);* Siqi Bai *(Missouri University of Science and Technology, Rolla, MO, USA);* Xinyun Guo *(Missouri University of Science and Technology, Rolla, MO, USA);* Shuai Jin *(Missouri University of Science and Technology, Rolla, MO, USA);* Yaojiang Zhang *(Missouri University of Science and Technology, Rolla, MO, USA);* Joakim Eriksson *(Microsoft Mobile (China) Investment Co. Ltd., Beijing, China);* Lijuan Qu *(Microsoft Mobile (China) Investment Co. Ltd., Beijing, China);* Jingyu Huang *(Microsoft Device Group, San Diego, CA, USA);* Jun Fan *(Missouri University of Science and Technology, Rolla, MO, USA)*
Best Student Paper Award Finalist

2:30 pm **A Planar Low-Profile Meander Antenna Design for Wireless Terminal Achieving Low Self-Interference** 320
Yihong Qi *(DBJ Technologies, Zhuhai, China);* Jun Fan *(Missouri University of Science and Technology, Rolla, MO, USA);* Ye-Hai Bi *(Shenzhen Sunway Communication Co., Ltd, ShenZhen, China);* Wei Yu *(DBJ Technologies, Zhuhai, China);* Jim Drewniak *(Missouri University of Science and Technology, Rolla, MO, USA)*
Best EMC Paper Award Finalist

3:30 pm **Near-Field Coupling Estimation by Source Reconstruction and Huygens's Equivalence Principle** 324
Liang Li *(Missouri University of Science and Technology, Rolla, MO, USA);* Jingnan Pan *(Missouri University of Science and Technology, Rolla, MO, USA);* Chulsoon Hwang *(Samsung Electronics Co., Ltd, Suwon, South Korea);* Gyuyeong Cho *(Samsung Electronics Co., Ltd, Suwon, South Korea);* Harkbyeong Park *(Samsung Electronics Co., Ltd, Suwon, South Korea);* Yaojiang Zhang *(Missouri University of Science and Technology, Rolla, MO, USA);* Jun Fan *(Missouri University of Science and Technology, Rolla, MO, USA)*
Best EMC Paper Award Finalist and Best Student Paper Award Finalist

4:00 pm **Eliminating Non-Linear RSS Reporting Error in a Radiated RSS-Based TIS Testing Method** 330
Penghui Shen *(Hunan University, Changsha, China);* Yihong Qi *(DBJ Technologies, Zhuhai, China);* Wei Yu *(DBJ Technologies, Zhuhai, China);* Fuhai Li *(Hunan University, Changsha, China);* Jun Fan *(Missouri University of Science and Technology, Rolla, MO, USA)*
Best Student Paper Award Finalist

TH-PM-2 Numerical Modeling and Simulation Techniques II

Chair: Kai Xiao, Intel Corporation, Dupont, WA, USA
Co-Chair: Gerardo Romo, Qualcomm Technologies, Inc., San Diego, CA, USA

1:30 pm **Frequency-Domain Interpolation Problems for Long Structures** 335
Mikheil Tsiklauri *(Missouri University of Science and Technology, Rolla, MO, USA);*
Mikhail Zvonkin *(Missouri University of Science and Technology, Rolla, MO, USA);*
Nana Dikhaminjia *(Missouri University of Science and Technology, Rolla, MO, USA);*
Jun Fan *(Missouri University of Science and Technology, Rolla, MO, USA);*
James L. Drewniak *(Missouri University of Science and Technology, Rolla, MO, USA)*

TH-PM-3 Power Integrity and Power Delivery Network II

Chair: A. Ege Engin, San Diego State University, San Diego, CA, USA
Co-Chair: Yujeong Shim, Altera Corporation, San Jose, CA, USA

1:30 pm **Integrated Power Supply Packaging Technique with Reduced Parasitic Inductance for On-Die Voltage Regulator Design and Application** 341
Boping Wu *(Intel Corporation, Hillsboro, OR, USA);*
Shaowu Huang *(Intel Corporation, DuPont, WA, USA)*

4:00 pm **Real-Time Programmable VR for Power Delivery Efficiency Enhancement** 345
Wei Shen *(Intel Corporation, Shanghai, China);* Weixia Liang *(Intel Corporation, Shanghai, China);*
Herry Hu *(Intel Corporation, Shanghai, China)*

TH-PM-4 Special Session: Uncertainty Quantification in Computational EM and Signal/Power Integrity Verification

Chair: Branislav Notaros, Colorado State University, Fort Collins, CO, USA
Co-Chair: Sourajeet Roy, Colorado State University, Fort Collins, CO, USA

1:30 pm **Efficient Multidimensional Statistical Modeling of High Speed Interconnects in SPICE via Stochastic Collocation using Stroud Cubature** 350
Majid Ahadi *(Colorado State University, Fort Collins, CO, USA);*
Mounica Vempa *(Colorado State University, Fort Collins, CO, USA);*
Sourajeet Roy *(Colorado State University, Fort Collins, CO, USA)*

2:00 pm **A Polynomial Chaos Approach for EM Uncertainty Propagation in 3D-FDTD Magnetized Cold Plasma** 356
Bach T. Nguyen *(University of Utah, Salt Lake City, UT, USA);* Alireza Samimi *(University of Utah, Salt Lake City, UT, USA);* Jamesina J. Simpson *(University of Utah, Salt Lake City, UT, USA)*

2:30 pm **Efficient Multi-Parameteric Uncertainty Quantification Methods for EMC/EMI Applications** 361
Zixi Gu *(University of Toronto, Toronto, ON, Canada);* Xingqi Zhang *(University of Toronto, Toronto, ON, Canada);* Neeraj Sood *(University of Toronto, Toronto, ON, Canada);*
Costas D. Sarris *(University of Toronto, Toronto, ON, Canada)*

3:30 pm **Studying the Effect of Drilling Uncertainty on Signal Propagation through Vias** 365
Yansheng Wang *(Missouri University of Science and Technology, Rolla, MO, USA);*
Srinath Penugonda *(Missouri University of Science and Technology, Rolla, MO, USA);*
Yaojiang Zhang *(Missouri University of Science and Technology, Rolla, MO, USA);*
Ji Chen *(University of Houston, Houston, TX, USA);* Jun Fan *(Missouri University of Science and Technology, Rolla, MO, USA)*